



CoventorWare™

Design Tool for Bio-MEMS & Microfluidics

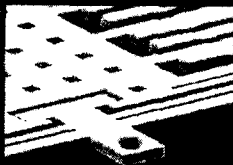
2003. 12. 05 ~ 06

Seungoh Han
CoventorWare AE, DavanTech

CoventorWare™ Addresses Most MEMS Applications

Sensing

Pressure sensors
Accelerometers
Gyroscopes
Microphones
Mass spectrometers

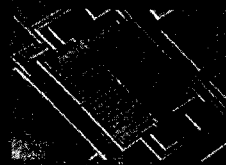


Optics

Mirrors
VOAs
Tunable lasers

RF

Switches
Varactors
Resonators
(FBAR, SAW)

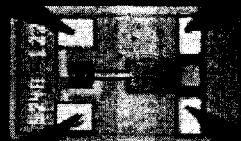


Actuators

DC relays
Data storage

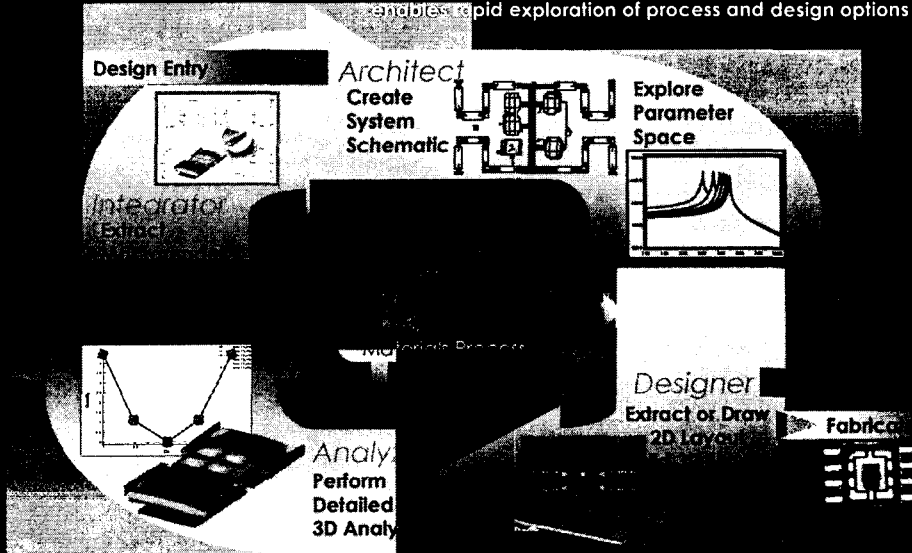
Microfluidics

Inkjet heads
Dispensing
Lab-on-chip
Fuel cells
Cell sorting



CoventorWare - Design Flow

The only comprehensive, integrated suite of tools for MEMS that enables rapid exploration of process and design options



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Process-Centric Design Flow

Start by specifying the manufacturing process

Process centric



Process description

Step	Name	Type	Layer	Material	Thickness	Time	Temp	Pressure	Flow	Pressure	Flow
1	Substrate	Substrate	Substrate	Si	500um						
2	Deposit	Deposit	SiO2	SiO2	100nm						
3	Etch	Etch	SiO2	SiO2		10min	100C	1000mbar	1000ml/min		
4	Deposit	Deposit	Cr	Cr	10nm						
5	Etch	Etch	Cr	Cr		10min	100C	1000mbar	1000ml/min		
6	Deposit	Deposit	Al	Al	100nm						
7	Etch	Etch	Al	Al		10min	100C	1000mbar	1000ml/min		
8	Deposit	Deposit	Si3N4	Si3N4	100nm						
9	Etch	Etch	Si3N4	Si3N4		10min	100C	1000mbar	1000ml/min		
10	Deposit	Deposit	SiO2	SiO2	100nm						
11	Etch	Etch	SiO2	SiO2		10min	100C	1000mbar	1000ml/min		
12	Deposit	Deposit	SiO2	SiO2	100nm						
13	Etch	Etch	SiO2	SiO2		10min	100C	1000mbar	1000ml/min		
14	Deposit	Deposit	SiO2	SiO2	100nm						
15	Etch	Etch	SiO2	SiO2		10min	100C	1000mbar	1000ml/min		
16	Deposit	Deposit	SiO2	SiO2	100nm						
17	Etch	Etch	SiO2	SiO2		10min	100C	1000mbar	1000ml/min		
18	Deposit	Deposit	SiO2	SiO2	100nm						
19	Etch	Etch	SiO2	SiO2		10min	100C	1000mbar	1000ml/min		
20	Deposit	Deposit	SiO2	SiO2	100nm						
21	Etch	Etch	SiO2	SiO2		10min	100C	1000mbar	1000ml/min		
22	Deposit	Deposit	SiO2	SiO2	100nm						
23	Etch	Etch	SiO2	SiO2		10min	100C	1000mbar	1000ml/min		
24	Deposit	Deposit	SiO2	SiO2	100nm						
25	Etch	Etch	SiO2	SiO2		10min	100C	1000mbar	1000ml/min		
26	Deposit	Deposit	SiO2	SiO2	100nm						
27	Etch	Etch	SiO2	SiO2		10min	100C	1000mbar	1000ml/min		
28	Deposit	Deposit	SiO2	SiO2	100nm						
29	Etch	Etch	SiO2	SiO2		10min	100C	1000mbar	1000ml/min		
30	Deposit	Deposit	SiO2	SiO2	100nm						

Materials database

Material	Layer	Thickness	Material	Layer	Thickness
Substrate	Substrate	500um	Si	Substrate	500um
SiO2	SiO2	100nm	SiO2	SiO2	100nm
Cr	Cr	10nm	Cr	Cr	10nm
Al	Al	100nm	Al	Al	100nm
Si3N4	Si3N4	100nm	Si3N4	Si3N4	100nm
SiO2	SiO2	100nm	SiO2	SiO2	100nm

Materials and Process data are shared by ARCHITECT and DESIGNER

Saves time by eliminating double entry of data

Makes it easy to explore effects of process variations on device performance in ARCHITECT™

Clean User Interface

Easy to use, prevents input errors

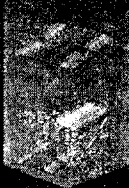
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ARCHITECT™ Key Benefits



ARCHITECT



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Evaluate device architectures rapidly

- Explore wide design space
- Quickly determine viable solutions

Perform thorough parametric variation

- Optimize performance with sensitivity analysis
- Account for fabrication tolerances to assure a working design

Evaluate multiple aspects of performance

- Transient, packaging, damping, RF, optics,
- Co-design device and system

Automatic Schematic driven layout (SDL) extraction

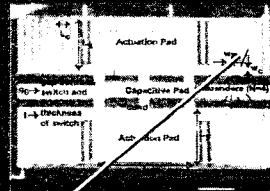
- Behavioral model geometries are converted to physical 2D layout descriptions
- Optimized material property descriptions are ported back into the FEM front end

Accelerate your time-to-market

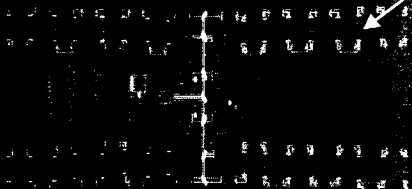
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ARCHITECT™ – a new MEMS design paradigm

- Create device schematic from library of MEMS-specific "parametric elements"
- Simulate device behavior within sub-system rapidly and accurately
- Perform Monte-Carlo and Sensitivity analyses to optimize design



S.P. Pacheco, L.P.B. Katehi, and C.T. Coventor, Design of Low-Actuation Voltage RF MEMS Switch, Proceedings of the 2000 IEEE IMS, Boston, MA, June 11-16, 2000.



RF Switch Schematic

Beam

Parameters

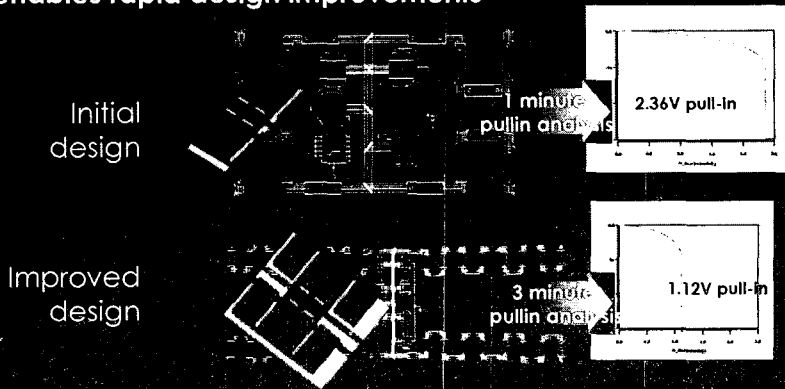
- Length & width
- Cross section
- Material properties
- Tolerances
- Top and bottom electrodes
- Curvature
- Sacrificial layer thickness
- Electrode thickness
- Electrode relative permittivity
- Mirror-electrode height ratio
- Mirror-electrode width ratio
- Gimbalelectrode offset
- Bias voltage
- Many more

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ARCHITECT™ – the fastest way to optimize a MEMS design

Example: Ability to quickly simulate RF switch enables rapid design improvements



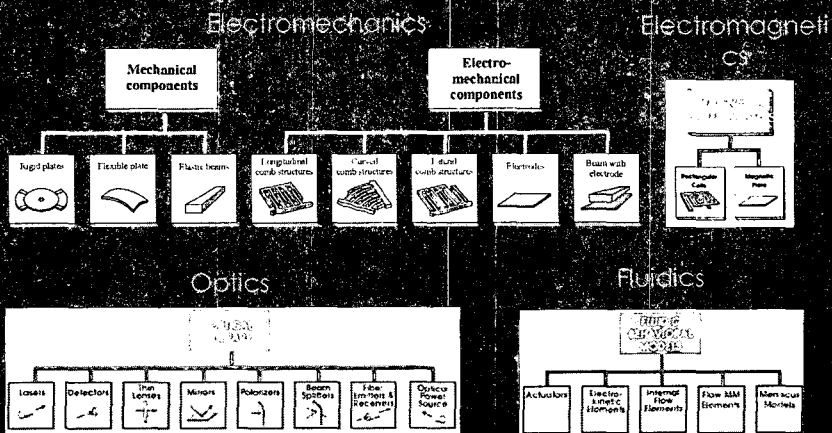
Examples of Simulation Capabilities

- Electrostatic force behavior
- Mechanical deflection
- Sensitivity analysis
- Transient electromechanical behavior
- Frequency response
- Monte Carlo analysis

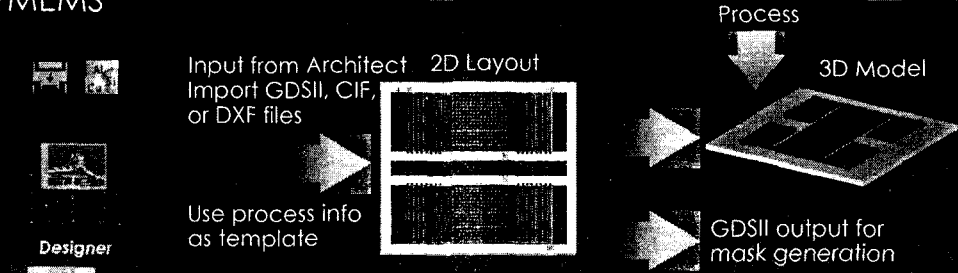


Comprehensive Library of Parametric Elements

Each element (component) is an analytical model that captures essential MEMS physics



DESIGNER™ – 2D layout and 3D modeling for MEMS



- Inputs from other layout tools, standard mechanical formats, and from schematics generated descriptions
- Fully functional GDS II layout editor for MEMS
- Combine 2D Layout with Process description to build a 3D Solid Model
- Output masks to be used by foundry for fabrication

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PHILIPAIN
DESIGN & CONSULTING

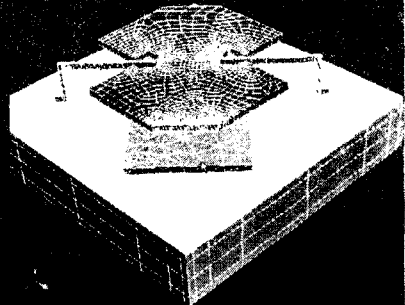
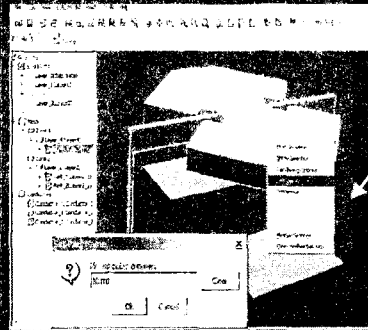
Designer - State-of-the-Art 3D Preprocessor

Saves Time

- Multi-select and name patches and conductors
- Patch and conductor names survive re-meshing
- Intuitive, synchronized "tree view"

Produces Better Meshes

- Apply best mesher for each layer
- Refine mesh locally, on faces, edges or vertices
- Get immediate feedback on mesh quality
- Snaps middle vertices of parabolic elements to true geometry



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ANALYZER™ – comprehensive coverage of Microfluidics



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Microfluidics

- Compressible and incompressible flows
- Laminar analysis
- Bouyancy driven flow (temperature dependent variable density)
- Newtonian and non-Newtonian
- Viscosity models such as Bingham, Carreau, power-law shear thinning
- Steady-state or transient
- Multiple species transport by Electrokinetics (EP, EO, DEP)
- Multiphase flow including pressure driven & surface tension driven flow
- Electrohydrodynamics: Electrostatic droplet manipulation
- Reaction Chemistry including Enzyme kinetics
- Fluid-Structure Interaction
- Non-inertial reference frame



INTEGRATOR™ – Macromodel Extraction



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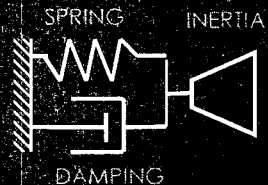
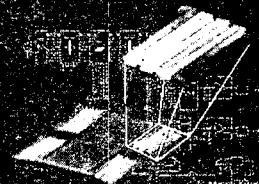
Extract Reduced-Order Models for Integration with...

- Control electronics
- Architect schematics - add custom components

Features

- New, intuitive interface includes all essential dynamics
 - SpringMM
 - DampingMM
 - InertiaMM
 - FlowMM
- New springs: Electromechanical and Double-Ended
- Extracted models are fully compatible with parametric models in ARCHITECT
- Generates Verilog-A templates too!

NOTE: INTEGRATOR was formerly known as SYSTEM BUILDER



Important applications of CoventorWare

- ✓ Conventional pressure-driven analysis
- ✓ thermo-capillary analysis for micro-cooling system
- ✓ multi-fluids mixing analysis
- ✓ micro-pump analysis driven by PZE, electrostatic, bubble, etc
- ✓ electrokinetics such as EP, EO, and DEP
- ✓ bead analysis
- ✓ inkjet design including nozzle analysis
- ✓ chemical reactions for hybridization, enzyme-related application, etc
- ✓ coupled physics analysis including moving structure and so on



Take-Away Messages about CoventorWare™

Provides the only complete end-to-end design methodology for MEMS today

Works with best-of-breed EDA tools such as Cadence and Synopsys

Can be flexibly configured to suit customer preferences – go with the entire end-to-end flow or choose from behavioral system modeling or FEA modules

ARCHITECT™ / DESIGNER™ can serve as a front end to other popular field solver suites from Ansys, Ansoft, Agilent, Fluent and Flow3D

Product is industrial strength

- Battle tested with 150+ commercial customers
- Used in 400+ universities as a research and teaching tool
- Used by Coventor in dozens of successful professional services programs

The best-in-class solution

